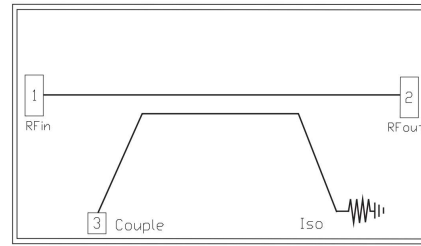


Performance

- Frequency: 15~40GHz
- Coupling: 20dB
- Coupling Flatness: 2dB
- Chip size: 1.55*0.9*0.1mm

Function Diagram

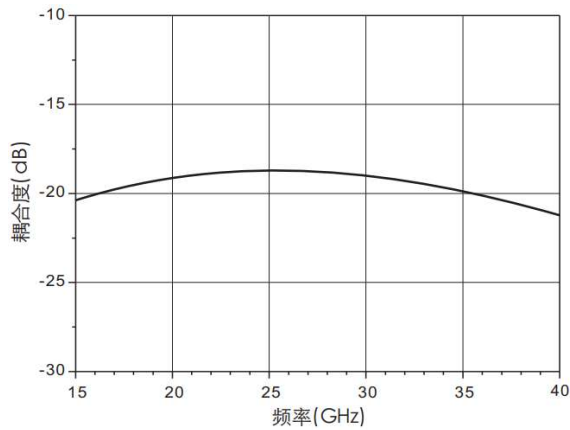


Electrical Specifications (Ta=+25°C, 50Ω system)

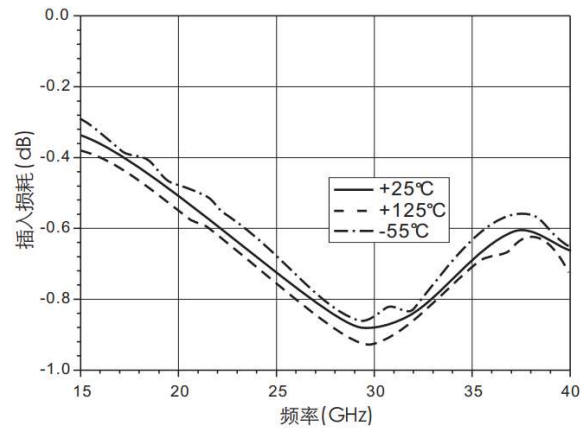
Parameter	Min	Typical	Max	Unit
Frequency Range	15~40			GHz
Coupling	19	20	21	
Insertion Loss	0.3	0.7	1	dB
Input Return loss	14	18	-	dB
Thru Output Return loss	13	20	-	dB
Coupling Output Return loss	14	20	-	dB

Test Curves (Die chip + Bonding line test)

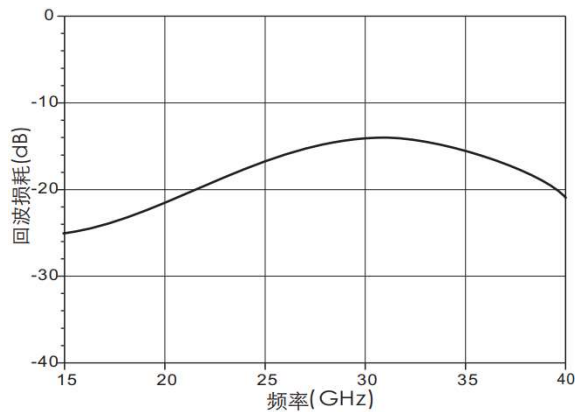
Coupling vs. Freq



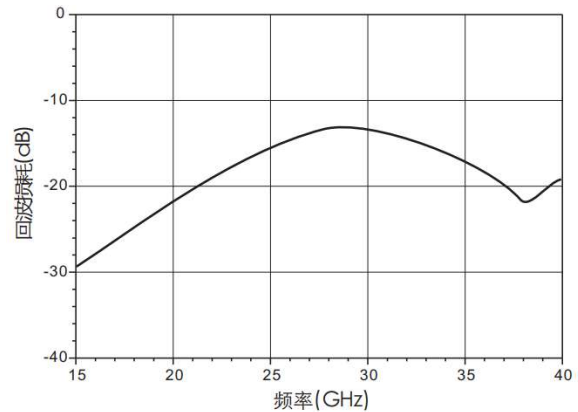
Insertion loss vs. Freq



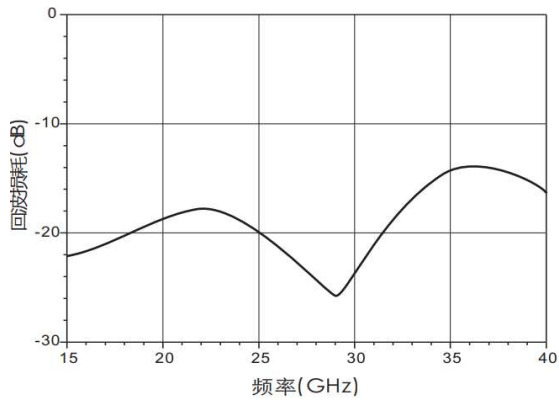
Input Return Loss vs. Freq



Thru output Return loss vs. Freq



Coupling Output Return Loss



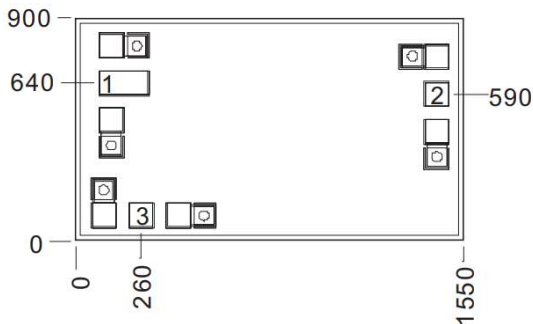
Absolute Rating

Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Max Input Power	2W
Static Protection (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Size



Note:

Unit: μm

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated, size: $100 \times 100 (\mu\text{m})$
4. Don't bonding on thru holds
5. Tolerance: $\pm 50 \mu\text{m}$

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50ohm
3	Couple	Coupling output port, 50ohm

Application

